



SPECIFICATION

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C100JB8NNNC

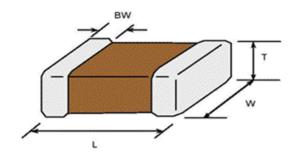
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 10pF, 50V, ± 5%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>100</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>O</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ①

| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | | | |
|---|---------------|---------------------------------------|-------------------|-------------------------|--|--|
| 2 | Size | 0603 (inch code) | L: 1.60 ± 0.10 mm | W: 0.80 ± 0.10 mm | | |
| 3 | Dielectric | C0G | Inner electrode | Ni | | |
| 4 | Capacitance | 10 pF | Termination | Cu | | |
| ⑤ | Capacitance | ± 5 % | Plating | Sn 100% (Pb Free) | | |
| | tolerance | | Product | Normal | | |
| 6 | Rated Voltage | 50 V | Special | Reserved for future use | | |
| 7 | Thickness | 0.80 ± 0.10 mm | ① Packaging | Cardboard Type, 7" reel | | |

B. Structure and dimension



| Samsung P/N | Dimension(mm) | | | | |
|-----------------|---------------|-------------|-------------|-------------|--|
| (Lead Free) | L | W | Т | BW | |
| CL10C100JB8NNNC | 1.60 ± 0.10 | 0.80 ± 0.10 | 0.80 ± 0.10 | 0.30 ± 0.20 | |

C. Samsung Reliability Test and Judgement condition

| Considered Within applified televenes | | | | | | |
|---|---|--|--|--|--|--|
| Capacitance Within specified tolerance 1 Mb±10% 0.5~5 | 1Mb±10% 0.5~5Vrms | | | | | |
| Q 600 min | | | | | | |
| Insulation 10,000Mohm or 500Mohm×μF Rated Voltage 60~12 | 20 sec. | | | | | |
| Resistance Whichever is smaller | | | | | | |
| Appearance No abnormal exterior appearance Microscope ('10) | Microscope ('10) | | | | | |
| Withstanding No dielectric breakdown or 300% of the rated volume | 300% of the rated voltage | | | | | |
| Voltage mechanical breakdown | | | | | | |
| Temperature C0G | | | | | | |
| Characteristics (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/ °C | (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃) | | | | | |
| Adhesive Strength No peeling shall be occur on the 500g×F, for 10±1 sec. | | | | | | |
| of Termination terminal electrode | | | | | | |
| Bending Strength Capacitance change : Bending to the limit (1mm) | Bending to the limit (1mm) | | | | | |
| within ±5% or ±0.5pF whichever is larger with 1.0mm/sec. | with 1.0mm/sec. | | | | | |
| Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder | SnAg3.0Cu0.5 solder | | | | | |
| is to be soldered newly 245±5°C, 3±0.3sec. | 245±5℃, 3±0.3sec. | | | | | |
| (preheating : 80~120 ℃ for | (preheating : 80~120 ℃ for 10~30sec.) | | | | | |
| | | | | | | |
| Resistance to Capacitance change : Solder pot : 270±5°C, 10± | Solder pot : 270±5℃, 10±1sec. | | | | | |
| Soldering heat within ±2.5% or ±0.25pF whichever is larger | | | | | | |
| Tan δ, IR : initial spec. | | | | | | |
| Vibration Test Capacitance change : Amplitude : 1.5mm | Amplitude : 1.5mm | | | | | |
| within ±2.5% or ±0.25pF whichever is larger From 10Hz to 55Hz (return | From 10Hz to 55Hz (return : 1min.) | | | | | |
| Tan δ, IR : initial spec. 2hours ´ 3 direction (x, y, z | 2hours ´3 direction (x, y, z) | | | | | |
| Moisture Capacitance change : With rated voltage | | | | | | |
| Resistance within ±7.5% or ±0.75pF whichever is larger 40±2℃, 90~95%RH, 500+ | 40±2°C, 90~95%RH, 500+12/-0hrs | | | | | |
| Q: 133.33 min | | | | | | |
| IR : 500Mohm or 25Mohm × μ F | | | | | | |
| Whichever is smaller | | | | | | |
| High Temperature Capacitance change : With 200% of the rate | d voltage | | | | | |
| Resistance within ±3% or ±0.3 pF whichever is larger Max. operating temperature | Max. operating temperature | | | | | |
| Q: 300 min 1000+48/-0hrs | | | | | | |
| IR : 1,000Mohm or 50Mohm × μ F | | | | | | |
| Whichever is smaller | | | | | | |
| Temperature Capacitance change : 1 cycle condition | 1 cycle condition | | | | | |
| | Min. operating temperature → 25°C | | | | | |
| | | | | | | |
| | | | | | | |
| | | | | | | |
| 5 cycle test | | | | | | |

^{*} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

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- ① Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- 4 Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- 6 Power plant control equipment
- Atomic energy-related equipment
- Undersea equipment
- Traffic signal equipment
- Data-processing equipment
- ## Electric heating apparatus, burning equipment
- Safety equipment
- ® Any other applications with the same as or similar complexity or reliability to the applications